**Section 307.7901 Semiconductor**

a) Applicability. This Section applies to discharges resulting from all process operations associated with the manufacture of semiconductors, except sputtering, vapor deposition, and electroplating.

b) Specialized Definitions. The Board incorporates by reference 40 CFR 469.12 (2003). This incorporation includes no later amendments or editions.

c) Existing Sources

1) The Board incorporates by reference 40 CFR 469.16 (2003). This incorporation includes no later amendments or editions.

2) No person subject to the pretreatment standards incorporated by reference in subsection (c)(1) may cause, threaten, or allow the discharge of any contaminant to a POTW in violation of those standards.

d) New Sources

1) The Board incorporates by reference 40 CFR 469.18 (2003). This incorporation includes no later amendments or editions.

2) No person subject to the pretreatment standards incorporated by reference in subsection (d)(1) may cause, threaten, or allow the discharge of any contaminant to a POTW in violation of those standards.

3) "New source" means any building, structure, facility, or installation whose construction commenced after August 8, 1982.

(Source: Amended at 47 Ill. Reg. 4662, effective March 23, 2023)